

## General Description

The MY005CNE3 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

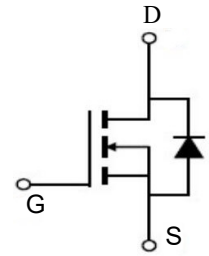
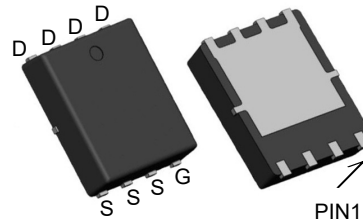


## Features

$V_{DSS}$	30	V
$I_D$	80	A
$R_{DS(ON)}(at V_{GS}=10V)$	<5.5	m $\Omega$
$R_{DS(ON)}(at V_{GS}=4.5V)$	<6.5	m $\Omega$

## Application

- Battery protection
- Load switch
- Uninterruptible power supply



## Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
MY005CNE3	PDFN3*3-8	005DN	5000

## Absolute Maximum Ratings ( $T_C=25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1,6</sup>	80	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS}$ @ 10V <sup>1,6</sup>	68	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	216	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	144.7	mJ
$I_{AS}$	Avalanche Current	53.8	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	69	W
$P_D@T_A=25^{\circ}C$	Total Power Dissipation <sup>4</sup>	5	W
$T_{STG}$	Storage Temperature Range	-55 to 175	$^{\circ}C$
$T_J$	Operating Junction Temperature Range	-55 to 175	$^{\circ}C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	62	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup> ( $t \leq 10s$ )	25	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	1.8	$^{\circ}C/W$

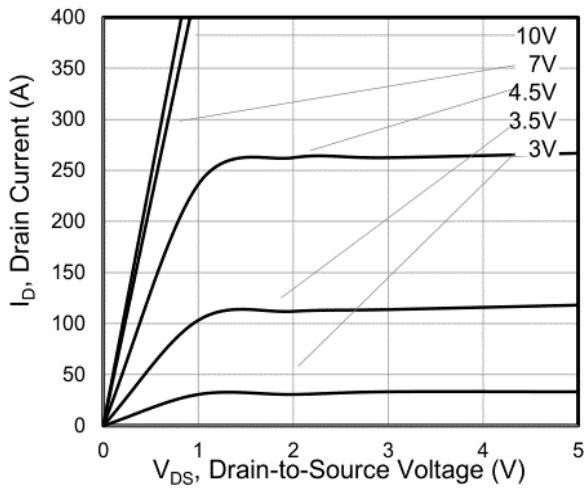
**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	30	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	0.0213	---	V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	---	4.3	5.5	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	---	4.8	6.5	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2	1.7	2.5	V
V <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	-5.73	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =30A	---	26.5	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	1.4	---	
Q <sub>g</sub>	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =15A	---	98	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	11	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	21	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =15V, V <sub>GS</sub> =10V, R <sub>G</sub> =3.3 I <sub>D</sub> =15A	---	17	---	ns
T <sub>r</sub>	Rise Time		---	41	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	55	---	
T <sub>f</sub>	Fall Time		---	66	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V, V <sub>GS</sub> =0V, f=1MHz	---	5471	---	pF
C <sub>oss</sub>	Output Capacitance		---	1628	---	
C <sub>riss</sub>	Reverse Transfer Capacitance		---	1026	---	
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	130	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	520	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =1A, T <sub>J</sub> =25°C	---	---	1.2	V

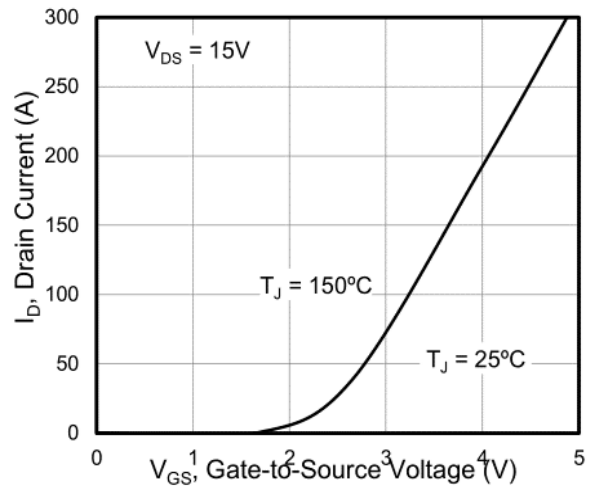
Note :

- 1.The data tested by surface mounted on a 1 inch 2 FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
- 3.The EAS data shows Max. rating . The test condition is V DD =25V,V GS =10V,L=0.1mH,I AS =53.8A
- 4.The power dissipation is limited by 175°C junction temperature
- 5.The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.
- 6.Package limitation current is 85A.

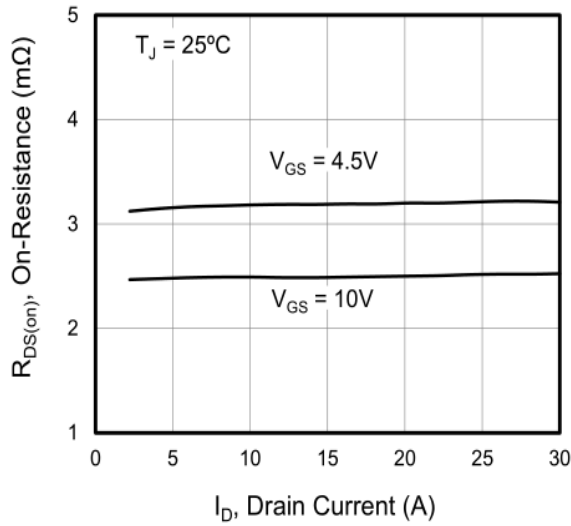
**Typical Characteristics**



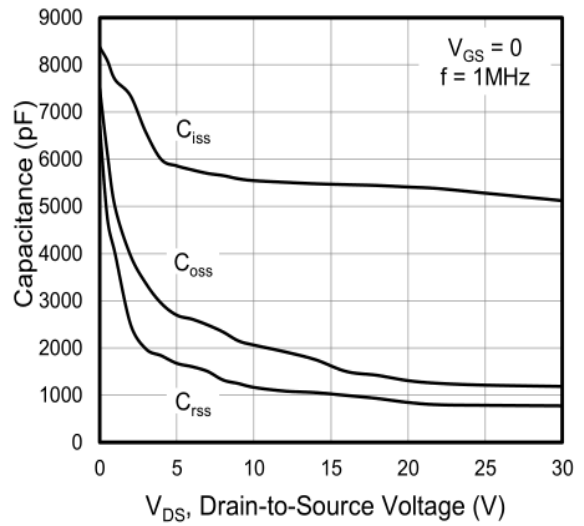
**Figure 1. Output Characteristics**



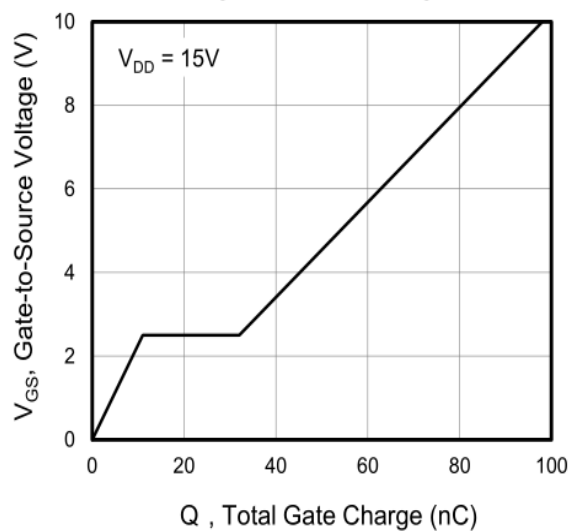
**Figure 2. Transfer Characteristics**



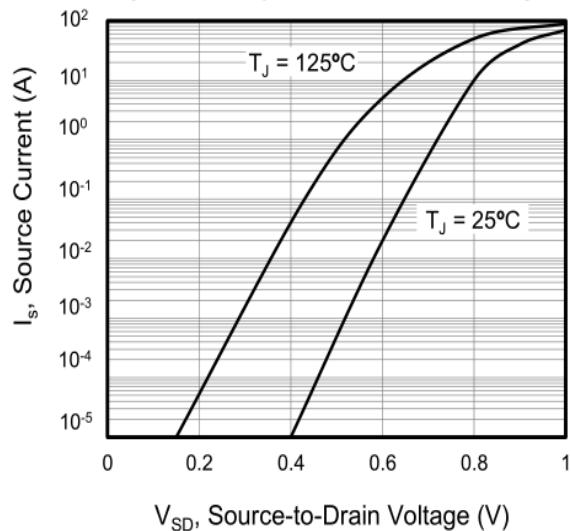
**Figure 3. On-Resistance vs. Drain Current**



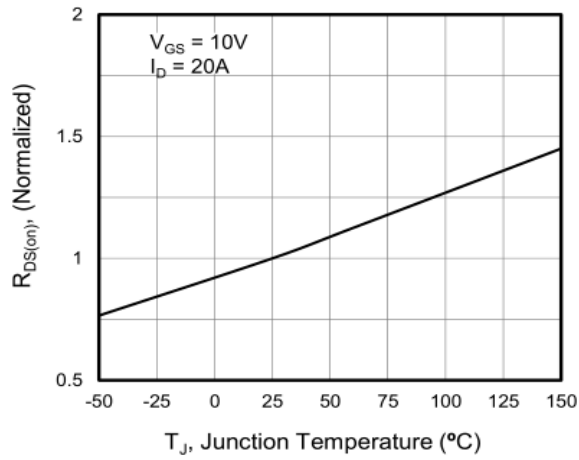
**Figure 4. Capacitance**



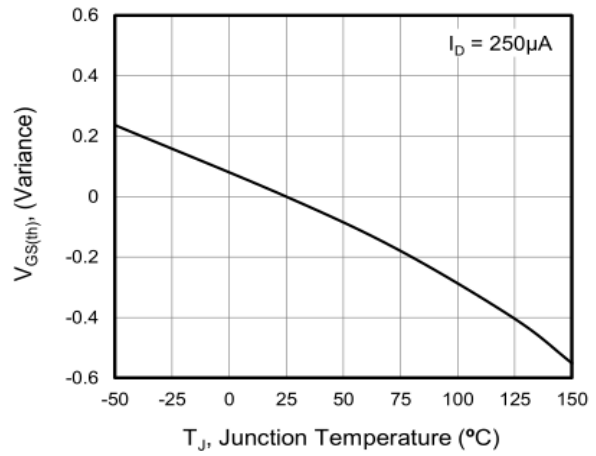
**Figure 5. Gate Charge**



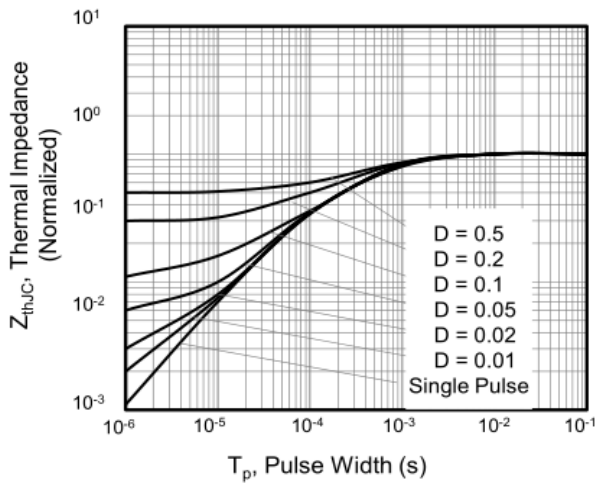
**Figure 6. Body Diode Forward Voltage**



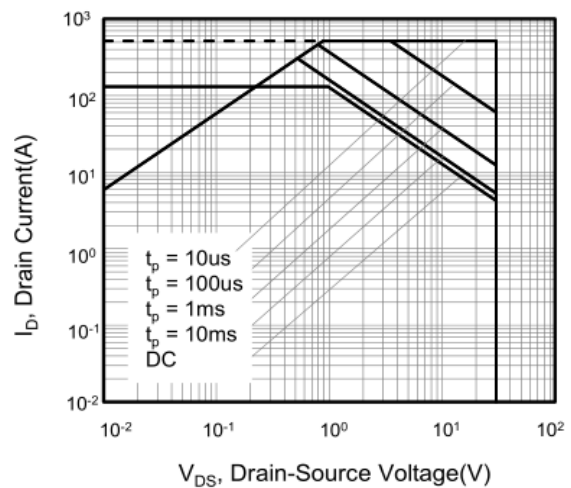
**Figure 7. On-Resistance vs. Junction Temperature**



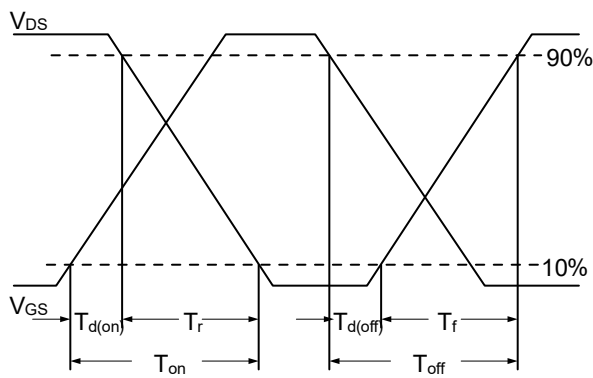
**Figure 8. Threshold Voltage vs. Junction Temperature**



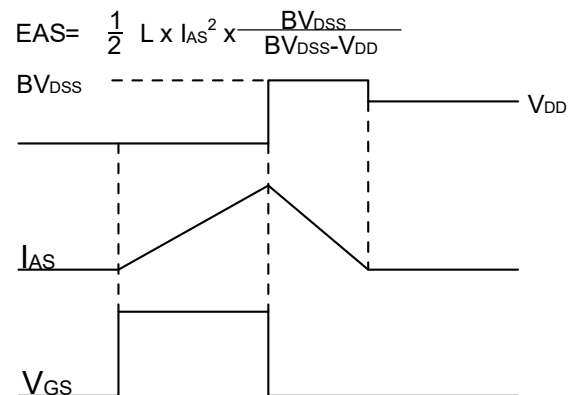
**Figure 9. Transient Thermal Impedance**



**Figure 10. Safe operation area**

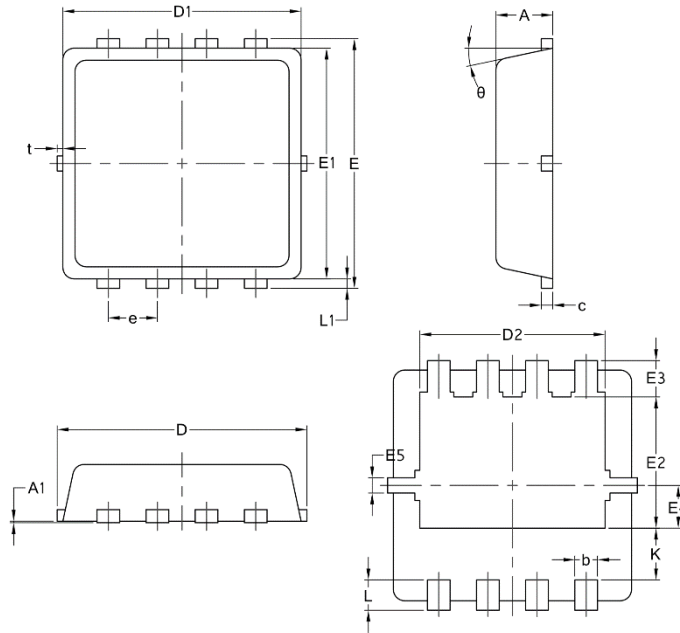


**Fig.11 Switching Time Waveform**



**Fig.12 Unclamped Inductive Switching Waveform**

**Package Mechanical Data-DFN3\*3-8L-JQ Single**



Symbol	Common		
	mm		
	Mim	Nom	Max
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
Φ	10	12	14